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PATENT ABSTRACTS OF JAPAN

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		(72) Inventor:	SUDA KOJI	

(54) SEMICONDUCTOR DEVICE

(57) Abstract:

PURPOSE: To reduce inductance, and to prevent the mathunction of a semicenductor device being generated by inductance by directly connecting a capacitor to outer leads for a power supply and a GND in the semiconductor device.

CONSTITUTION: A senticonductor chip 1 with pads 4A, 48 for a GND and a power supely is fined onto a package 2, to which outer leads 3 including outer leads 3A, for the CND and the pewer supely are formed and which contacts of ceramics, etc. The paid 4A, 48 for the GND and the power supely are connected respectively to the outer leads 3A als Per the GND and the power supply benefiting wires 6A, 6B, A capacitor 6 is fastered onto the outer leads 3A, 3B, and a terminal 7A for the GND and a terminal 7B for the power supply for the capacitor 5 are disectly connected respectively to the outer lead 3A for the GND and the outer lead 5B for the power supply. Accordingly, inductance is lowered, noises are reduced, and the generation of a maffunction can be prevented.

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